

# ABSTRACT

[Abstract]

[Problem to be Solved] To provide a measuring device preferable to enhance capability of pickup processing when picking up each chip of a plate-shaped member separated into a form of chips.

[Solution] A semiconductor wafer 4 as a plate-shaped member supported by a support H with an adhesive sheet 3 bonded to an opening of a ring frame 2 and separated into a form of chips by cutting is set as a measurement target. An image processing unit 5 measures a chip interval G and a shift angle  $\theta$ , and measurement data D of them is sent from the image processing unit 5 to a host computer 6, and stored in storage means 12 of the host computer 6. Based on the chip interval G and the shift angle  $\theta$  stored in the storage means 12, position recognition processing at the time of confirming the position of a chip with a recognition unit of a pickup device, for example, a camera, and correction processing of aligning the position of a collet for pickup with the recognized position can be carried out in the next step.

[Selected Drawing] Figure 1



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\*G00002\*